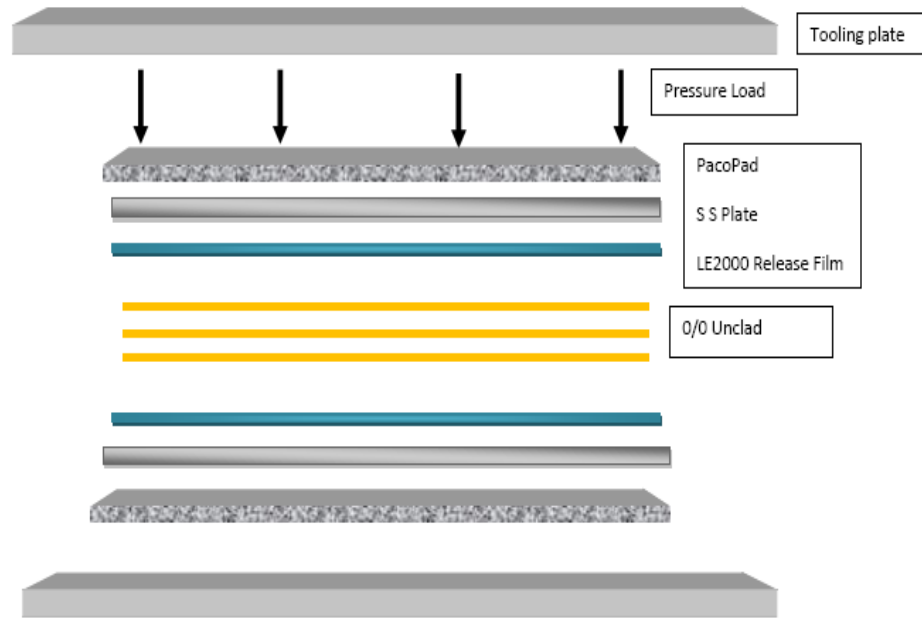


Product Specification

PRODUCT:

PACOTHANE LE 2000 is a two-sided Release Film engineered for Printed Circuit Board lamination. When used in applications it will consistently contain any resin squeeze-out while acting as a buffer to protect copper from damaged plates or other induced surface related imperfections." LE" 2000 is the preferred choice for sensitive lamination surfaces such as Unclad or Flex Kapton where a low extraction residue free surface release film is required and a heavier gauge of base film for easier handling is desired. Its low X-Y axis shrinkage stabilizes the stress effect from aluminum plates. "LE" can help reduce the frequency of plate cleaning and prevents press pads from sticking to press platens, tooling plates and bonding to tooling pins.

RECOMMENDED LAMINATION LAY-UP:



TECHNICAL DATA:

Physical Property		Test Method	Reported Units	Typical Values	
Max. Application Temp.		Q 1025	°F (°C)	400 (204)	
Thickness		Q 3019	mil (µm)	2.0 (50.8)	
Density		ASTM	g/cm ³	0.94	
Heat Shrinkage	MD	Q-1045	%	<5%	
	TD		%	<5%	
Melting Temp.		ASTM E794	°F (°C)	495°F (257°C)	
Appearance		White, Semi-translucent			
Tensile Strength (At yield point)	MD	YP	ASTM D882	Kg/cm ²	230
		Elong	ASTM D882	%	410
	TD	YP	ASTM D882	Kg/cm ²	190
		Elong	ASTM D882	%	520

SHELF LIFE & STORAGE:

- Material should be kept in dry and clean room, below 113°F (45 °C)

Note: Pacothane generates this data sheet and specifications that are just for reference. We cannot control the performance impact created from different process, storage and manufacturing variables.